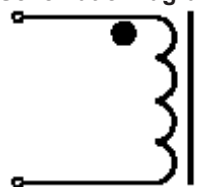


**RoHS
Compliant**



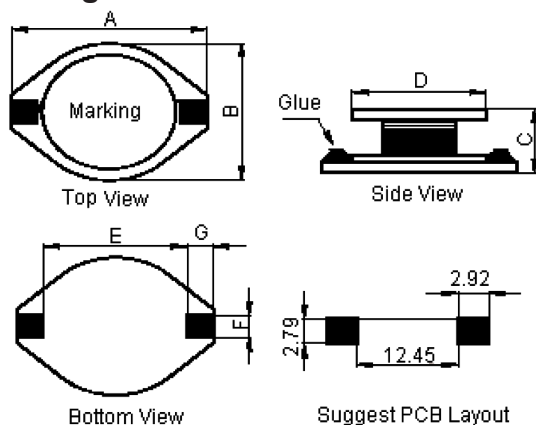
Schematic Diagram



Note:

1. Wire Ø0.4mm × 2P 2UEWF 155°C
2. 14.5TS (Reference)

Configurations and Dimensions



A	18.54mm (Max.)
B	15.24mm (Max.)
C	7.11mm (Max.)
D	12.7 ±0.3mm
E	12.92mm (Ref.)
F	2.54mm (Ref.)
G	2.54mm (Ref.)

Test Data for Mechanical

Test Item	A mm	B mm	C mm	D mm	E mm	F mm	G mm
Specification	18.54 (Max.)	15.24 (Max.)	7.11 (Max.)	12.7 ±0.3	12.92 (Ref.)	2.54 (Ref.)	2.54 (Ref.)
1	18.05	14.06	6.25	12.71	12.91	2.51	2.57
2	18.12	14.07	6.26	12.73	13.03	2.53	2.56
3	18.08	14.07	6.24	12.72	13.06	2.53	2.58
4	18.07	14.04	6.26	12.75	13.11	2.52	2.54
5	18.06	14.06	6.28	12.76	13.14	2.53	2.56
Average	18.08	14.06	6.26	12.73	13.05	2.52	2.56

Electrical Characteristics

Test Condition		
100kHz / 5mA	L	15µH ±20%
at 25°C	DCR	36mΩ (Max.)
100kHz / 0.25mA Irms = 4A	ΔT	Temperature rise 40°C (Max.)

Operating temperature : -55°C to +130°C

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Reliability Test

Test Item	Specifications	Test Method and Remarks
Operating temperature range	-55°C to +130°C	Including temperature rise due to self-generated heat.
Storage condition	Ambient temperature : 0°C to 40°C Humidity : Below 70% RH	To maintain the solderability of terminal electrodes, care must be taken to control temperature and humidity in the storage area.
Moisture sensitivity	Appearance : No abnormality : No damage DCR change : Within ±5% Inductance change : Within ±5%	According to J-STD-020B level 3 Test condition : 60°C 60% RH Test duration : 40 hrs Recovery : 1 to 2 hours of recovery under the standard condition after the removal from the test chamber.
Solderability	All termination shall exhibit a continuous solder coating free from defects for a minimum of 95% of the surface area of any individual lead.	According to J-STD-002B Steam aging category : 97°C 98% RH Steam aging duration : 8 hrs Solder : Lead-free solder Solder temperature : 260 ±5°C Dip time : 5 +0 / -0.5s

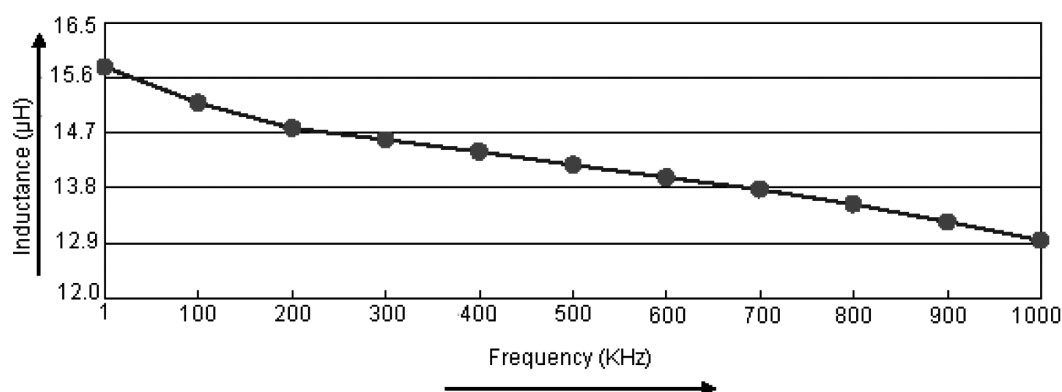
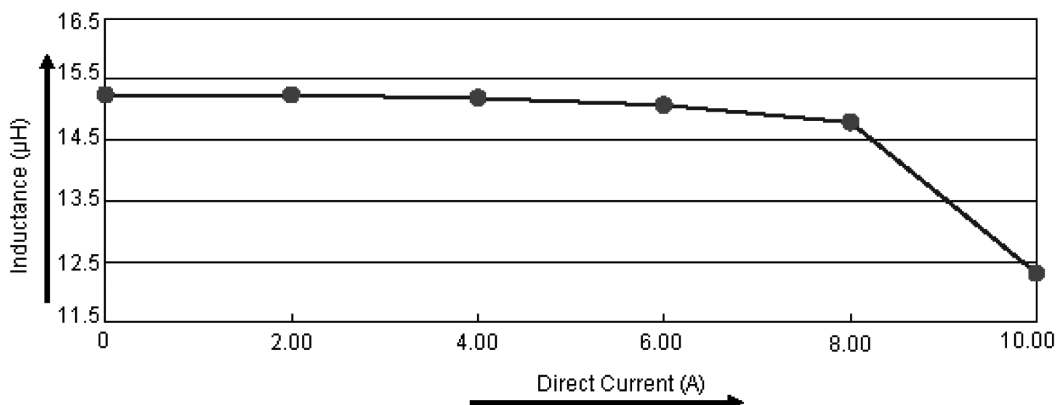
Test Data for Electrical

Test Item	L μH	DCR mΩ	ΔT
Condition	100kHz / 0.25V	at 25°C	100kHz / 0.25V I _{rms} = 4A
Specification	15 ±20%	36 (Max.)	Temperature rise 40°C (Max.)
1	15.35	30.32	OK
2	15.59	29.28	
3	15.45	30.36	
4	15.44	30.14	
5	15.63	30.18	
Average	15.49	30.056	OK

Material List

No.	Item	Material Description
1	Core	T2 DR12.7 x 5.6C B5.8 F3.3
2	Wire	Ø0.4mm x 2P 2UEWF 155°C
3	Solder (Lead Free)	Sn99.3% / Cu0.7%
4	Glue	TH320
5	Base	DAP HD127-3

Electric Characteristics



Part Number Table

Description	Part Number
Inductor, 15μH, 20%, 4.5Arms	MCBF7330-150MU

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